Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP 501 Wireless Client Bridge (J9835A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver with center cavity (tamper-resistant)	T10
Wire cutters	
Needle nose pliers	
Flat blade screwdriver	
Phillips screwdriver	P1

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Using a T10 Torx driver (tamper-resistant), remove the 8 screws securing the end plates to the chassis.
2. Using wire cutters, cut the wires holding the endplate opposite the Ethernet and console connectors.
3. Slide the other endplate still connected to the main PCA out of the chassis.
4. With an adjustable wrench, remove the 2 fasteners securing the console connector to the end plate.
5. Detach the 3 wires from the radio module PCA mounted on the main PCA.
6. Using needle nose pliers, compress the ends of each of the plastic fasteners (securing the heat sink over the radio module PCA) from the backside of the main PCA
7. Remove the plastic fasteners.
8. Using a flat blade screwdriver, pry the heat sink off the radio module PCA
9. Using P1 Phillips screw driver, remove the 2 screws securing the radio module PCA.
10. Remove the radio module PCA.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).